

Amendments to the Claims

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims

1. (currently amended) Machine for cutting an opening, such as a window in a planar substrate [(1)], said machine having at least a cutting tool [(12, 13)], a transfer system [(7, 8)] holding said substrate [(1)] and driving said substrate along a determined direction, and an aspiration box [(9)] to maintain the substrate [(1)] during the cutting operation, said cutting tool comprising a laser [(12)] generating a laser beam [(13)] that can be moved in two perpendicular directions and evacuation means [(9, 11; 15)] to evacuate a cut part of said substrate [(1)], wherein said aspiration box [(9)] is located on the same side of the substrate as said cutting tool [(12, 13)] and further comprises a bottom wall [(17)] with aspiration openings [(10)] against which said substrate [(1)] is aspirated and a cutting opening [(14)] through which said laser beam [(13)] is directed onto the substrate.

2. (currently amended) Machine according to claim 1, wherein said evacuation means [(9, 11)] evacuate the cut part by aspiration through said cutting opening [(14)].

3. (currently amended) Machine according to claim 1, wherein said evacuation means comprise an evacuation outlet [(15)] for evacuating the cut part by aspiration which is disposed on the other side of the substrate with respect to the surface [(17)] against which the substrate [(1)] is applied during the cutting operation.

4. (currently amended) Machine according to claim 3, wherein said cutting opening [(14)] is closed by a transparent material, such as glass.

5. (currently amended) Machine according to ~~any of the preceding claims~~ claim 1, wherein said transfer system is a chain gripper system [(7)] comprising a chain on which gripper bars [(8)] are mounted.

6. (currently amended) Machine according to ~~any of the preceding claims~~ claim 1, wherein said laser $[(12)]$ is displaced linearly or rotationally.

7. (currently amended) Machine according to ~~any of claims 1 to 5~~ claim 1, wherein said laser beam $[(13)]$ is displaced linearly or rotationally.

8. (currently amended) Machine according to ~~any one of the preceding claims~~ claim 1, further comprising a laminate application unit for applying a strip of laminate over the cut opening of the substrate.

9. (currently amended) Process for cutting an opening, such as a window, in a planar substrate $[(1)]$, said process being characterized by the following steps:

- holding said substrate $[(1)]$ with a gripper,
- moving said substrate $[(1)]$ along a given direction,
- applying said substrate $[(1)]$ against a surface $[(17)]$ by using air under depression,
- directing a laser beam $[(13)]$ onto said substrate $[(1)]$ through a cutting opening $[(14)]$ provided in said surface $[(17)]$ to cut an opening in said substrate,
- evacuating the cut part of said substrate $[(1)]$.

10. (currently amended) Process according to claim 9, wherein said cut part is evacuated by aspiration through said cutting opening $[(14)]$.

11. (currently amended) Process according to claim 9, wherein said cut part is evacuated by aspiration through an evacuation outlet $[(15)]$ disposed on the other side of the substrate $[(1)]$ with respect to the surface $[(17)]$ against which the substrate $[(1)]$ is applied during the cutting operation.

12. (currently amended) Process according to ~~any of claims 9 to 11~~ claim 9, wherein said laser $[(12)]$ is displaced linearly or rotationally.

13. (currently amended) Process according to ~~any of claims 9 to 11~~ claim 9, wherein said laser beam ~~[(13)]~~ is displaced linearly or rotationally.

14. (previously presented) Process according to claim 13, wherein a mirror displaces said laser beam.

15. (currently amended) Process according to ~~any of claims 9 to 14~~ claim 9, further comprising the step of applying laminate over the cut opening of the substrate.